Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

2SK2661

Chopper Regulator, DC–DC Converter and Motor Drive Applications

 $\begin{array}{ll} \bullet & \text{Low drain-source ON resistance} & : R_{DS} \, (\text{ON}) = 1.35 \, \Omega \, (\text{typ.}) \\ \bullet & \text{High forward transfer admittance} & : | \, Y_{fs} | = 4.0 \, S \, (\text{typ.}) \\ \bullet & \text{Low leakage current} & : \, I_{DSS} = 100 \, \mu A \, (\text{max}) \, (\text{V}_{DS} = 500 \, \text{V}) \\ \bullet & \text{Enhancement-mode} & : \, V_{th} = 2.0 \text{$^{\circ}$4.0 V} \, (\text{V}_{DS} = 10 \, \text{V, I}_{D} = 1 \, \text{mA}) \\ \end{array}$

Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	500	V
Drain-gate voltage (Ro	_{GS} = 20 kΩ)	V_{DGR}	500	V
Gate-source voltage		V _{GSS}	±30	V
Drain current	DC (Note 1)	I _D	5	Α
	Pulse (Note 1)	I _{DP}	20	Α
Drain power dissipation	n (Tc = 25°C)	P _D	75	W
Single pulse avalanche	e energy (Note 2)	E _{AS}	180	mJ
Avalanche current		I _{AR}	5	Α
Repetitive avalanche e	energy (Note 3)	E _{AR}	7.5	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature ra	ange	T _{stg}	-55~150	°C

Weight: 2.0 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.67	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 12.2 mH, R_G = 25 Ω , I_{AR} = 5 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

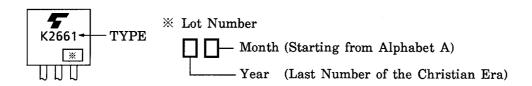
Electrical Characteristics (Ta = 25°C)

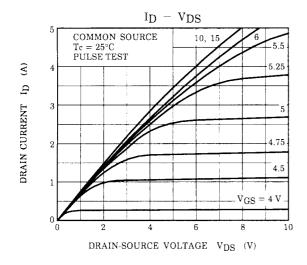
Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V _(BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	-	V
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V	_	_	100	μA
Drain-source bro	eakdown voltage	V _{(BR)DSS}	I_D = 10 mA, V_{GS} = 0 V	500	_	_	V
Gate threshold v	roltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source Of	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 2.5 A	_	1.35	1.50	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2.5 A	2.5	4.0	_	S
Input capacitano	е	C _{iss}			780	_	
Reverse transfer	capacitance	C _{rss}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	60	_	pF
Output capacitance		C _{oss}		_	200	_	
Switching time	Rise time	t _r	$V_{\rm GS}$ $\stackrel{10{\rm V}}{{}_{\rm 0V}}$ $\stackrel{I_{\rm D}=2.5{\rm A}}{{}_{\rm 0V}}$ $\stackrel{V_{\rm out}}{{}_{\rm RL}=90\Omega}$ $\stackrel{R_{\rm L}=90\Omega}{{}_{\rm VDD}=225{\rm V}}$	_	12	_	- ns
	Turn-on time	t _{on}		_	25		
	Fall time	t _f		_	15	ı	
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_W = 10 \mu s$	_	60	-	
Total gate charge (gate–source plus gate–drain)		Qg			17		
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		11	_	nC
Gate-drain ("miller") Charge		Q_{gd}			6	_	

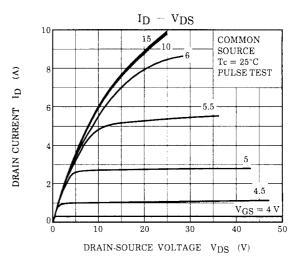
Source-Drain Ratings and Characteristics (Ta = 25°C)

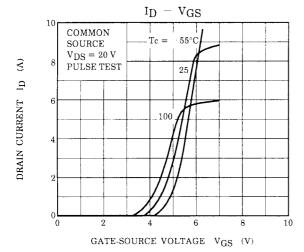
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	5	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	20	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 5 A, V _{GS} = 0 V	_	1400	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs	_	9	_	μC

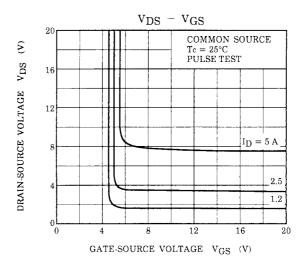
Marking

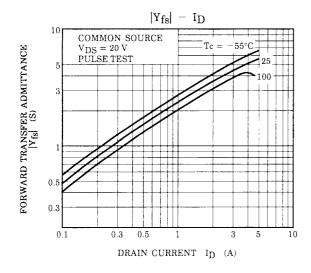


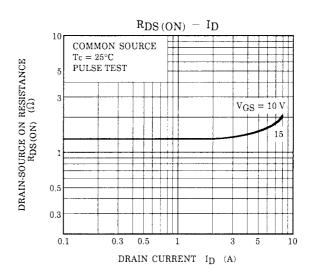




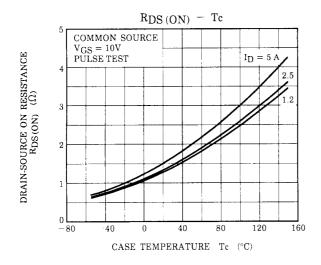


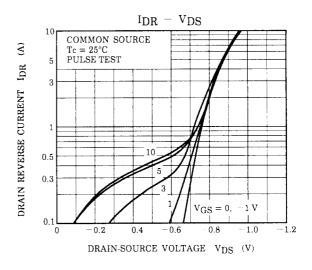


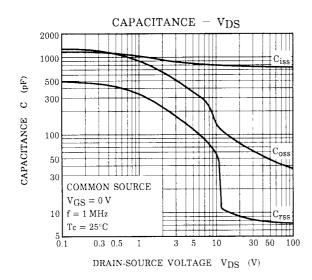


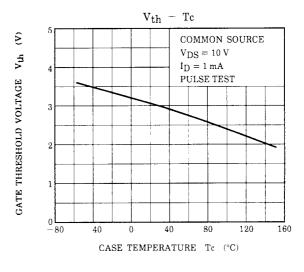


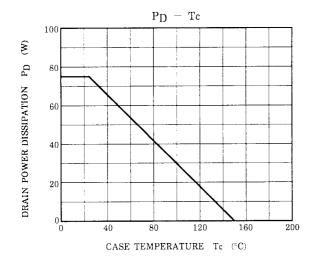
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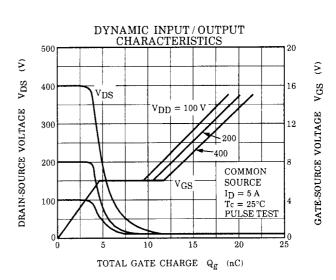




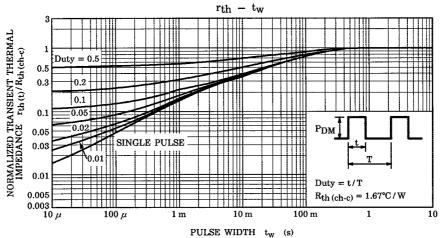


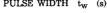


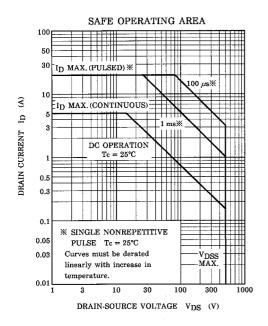


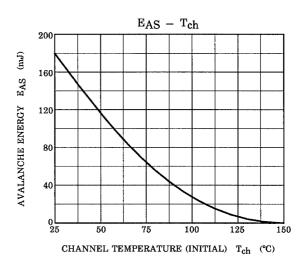


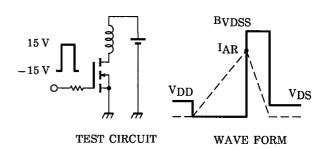
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$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 12.2~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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